### BONDING DIAGRAM

#### Diagram Description

The diagram illustrates the bonding configuration for a QFN36LA package. The bonding connections are shown with specific pin numbers and bonding locations.

#### Table

<table>
<thead>
<tr>
<th>L/F</th>
<th>QFN36LA</th>
<th>Mask No</th>
</tr>
</thead>
<tbody>
<tr>
<td>Stage</td>
<td>4.9x4.9mm (193x193mil)</td>
<td>Chip X</td>
</tr>
<tr>
<td>Epoxy</td>
<td>Wire Ø</td>
<td></td>
</tr>
</tbody>
</table>

#### Additional Notes

- **1 pin** indicates a specific connection point.

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**DWG No:** BA-NF-

**REV DATE**

NANTONG FUJITSU MICROELECTRONICS CO., LTD